

# LH6V4256

## CMOS 1M (256K × 4) Dynamic RAM

### FUNCTION

- 262,144 words × 4 bit
- Access time: 100 ns (MAX)
- Cycle time: 190 ns (MIN)
- Fast page mode cycle time: 60 ns (MIN)
- Power supply: +3.3 V ±0.3 V
- Power consumption (MAX):
  - Operating: 126 mW
  - Standby: 0.54 mW
- Built-in latch circuit for row-address, column-address, and input data
- $\overline{OE}$  = Don't care in early write operation
- $\overline{RAS}$  only refresh, hidden refresh, and  $\overline{CAS}$  before  $\overline{RAS}$  refresh capability
- On-chip refresh counter
- 512 refresh cycle/8 ms
- Packages:
  - 20-pin, 300-mil DIP
  - 26-pin, 300-mil SOJ
  - 28-pin, 8 × 13 mm<sup>2</sup> TSOP (Type I)

### DESCRIPTION

The LH6V4256 is a 262,144 word × 4-bit dynamic RAM which allows fast page mode access. The LH6V4256 is fabricated on SHARP's advanced CMOS double-level polysilicon gate technology. With its input multiplexed and packaged in the standard 20-pin DIP, 26-pin SOJ, or 28-pin TSOP (I) packages, it is easy to realize memory systems with low power dissipation and large memory capacity. The LH6V4256 operates on a single +3.3 V power supply and the built-in biasing voltage generator circuit.

### PIN CONNECTIONS

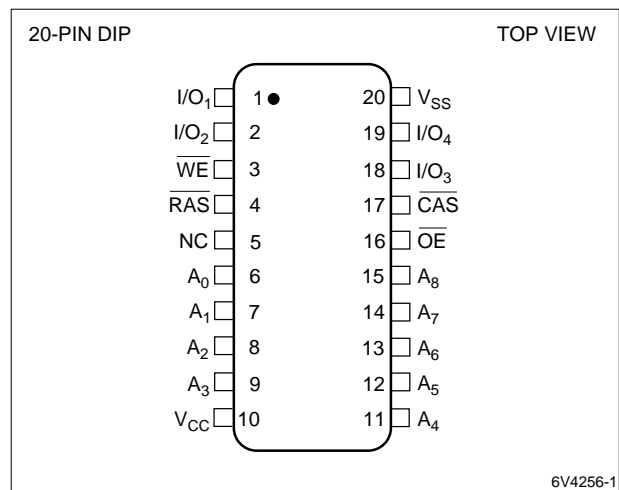


Figure 1. Pin Connections for DIP Package

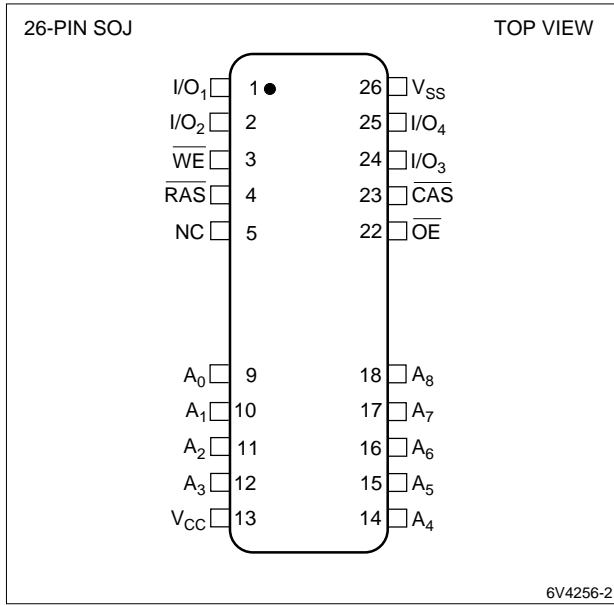


Figure 2. Pin Connections for SOJ Package

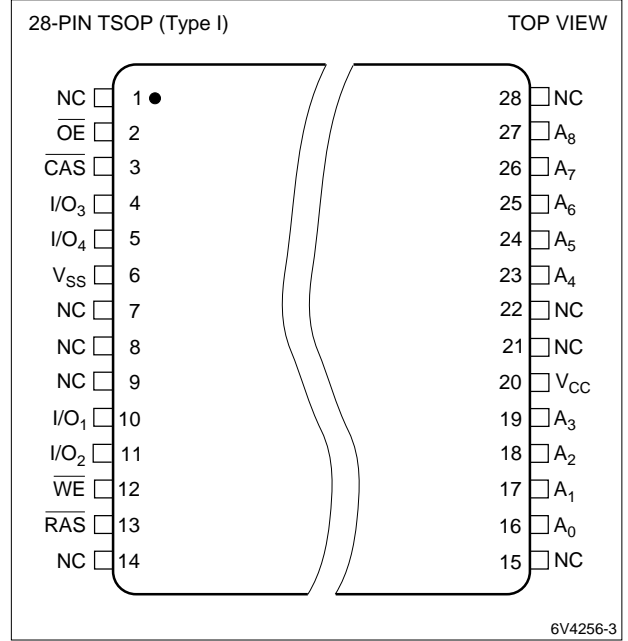


Figure 3. Pin Connections for TSOP Package

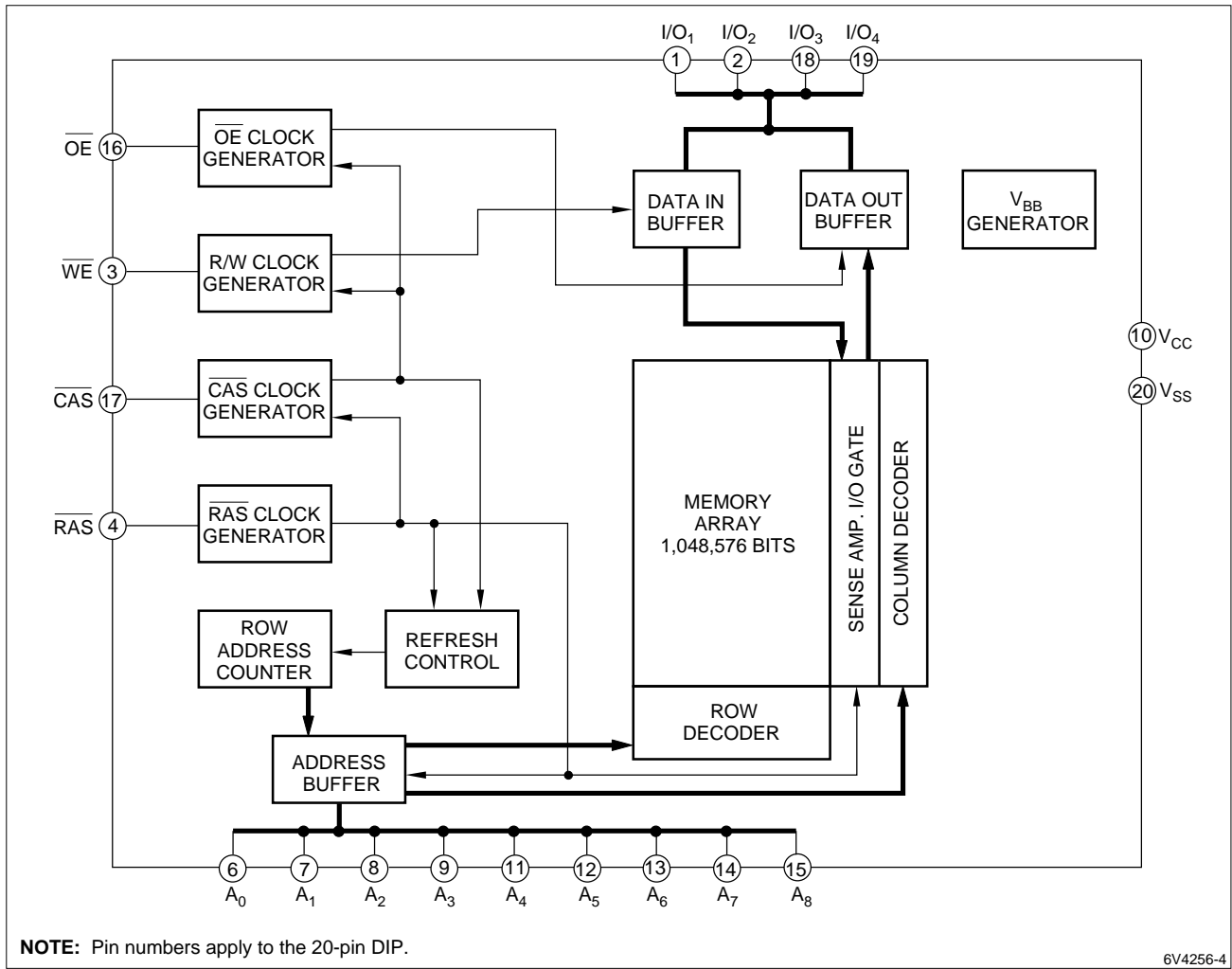


Figure 4. LH6V4256 Block Diagram

**PIN DESCRIPTION**

PIN NAME	FUNCTION
A <sub>0</sub> – A <sub>8</sub>	Address input
RAS	Row address strobe
CAS	Column address strobe
WE	Write enable
OE	Output enable

PIN NAME	FUNCTION
I/O <sub>1</sub> – I/O <sub>4</sub>	Data input/output
V <sub>CC</sub>	Power supply (+3.3 V)
V <sub>SS</sub>	Power supply (0 V)
NC	No connection

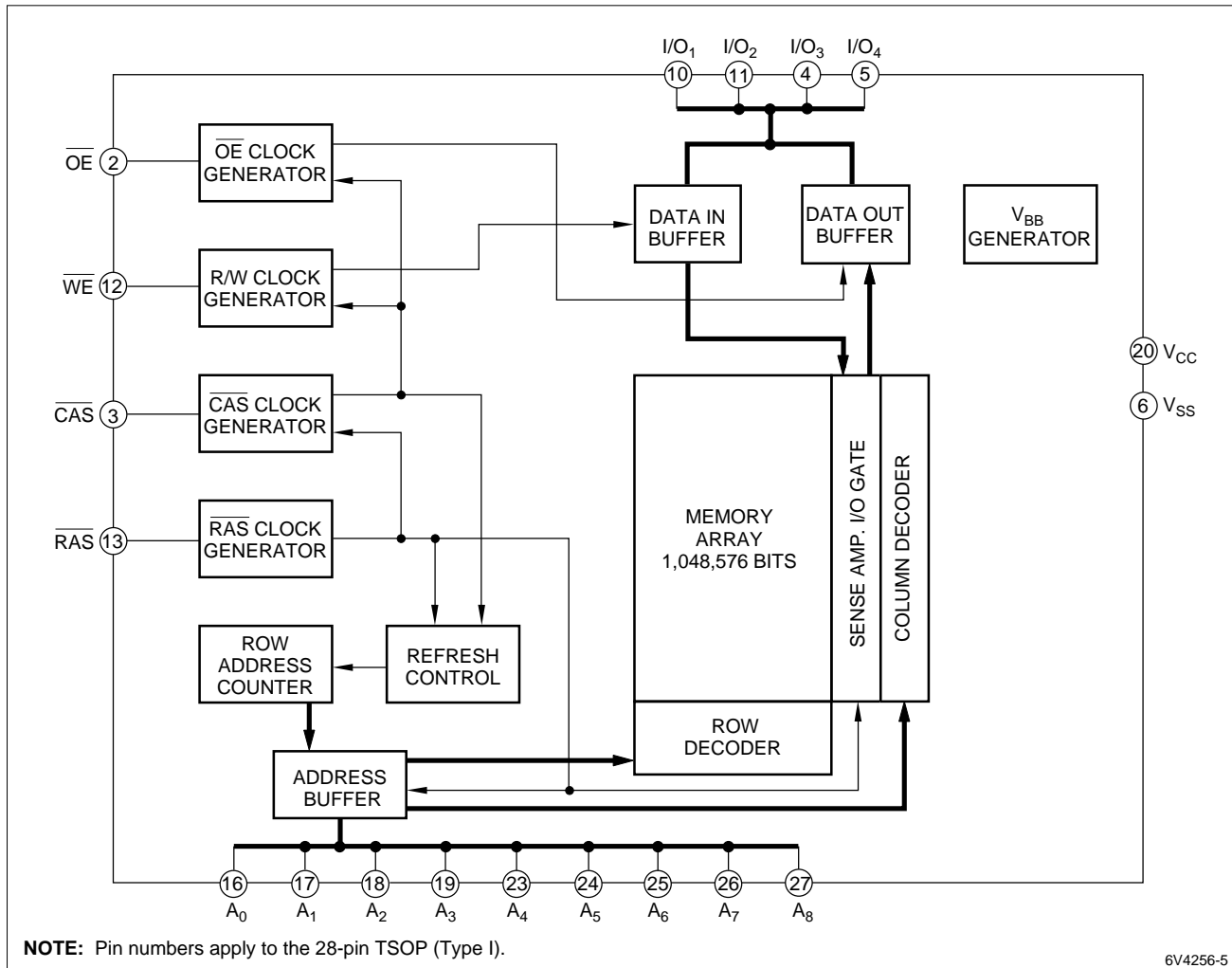


Figure 5. LH6V4256 Block Diagram

**ABSOLUTE MAXIMUM RATINGS**

PARAMETER	RATING	UNIT	NOTE
Applied voltage on all pins	-0.5 to +5.5	V	1
Output short circuit current	50	mA	
Power dissipation	1.0	W	
Operating temperature	0 to +70	°C	
Storage temperature	-65 to +150	°C	

**NOTE:**

1. The maximum applicable voltage on any pin with respect to  $V_{SS}$ .

**RECOMMENDED OPERATING CONDITIONS ( $T_A = 0$  to  $+70^\circ\text{C}$ )**

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT
Supply voltage	$V_{CC}$	3.0	3.3	3.6	V
	$V_{SS}$	0	0	0	V
Input voltage	$V_{IH}$	2.3		$V_{CC} + 0.3$	V
	$V_{IL}$	-0.3		0.6	V

**CAPACITANCE ( $T_A = 0$  to  $+70^\circ\text{C}$ ,  $f = 1$  MHz,  $V_{CC} = 3.3$  V  $\pm 0.3$  V)**

PARAMETER	CONDITIONS	SYMBOL	MIN.	MAX.	UNIT
Input capacitance	$A_0 - A_8$	$C_{IN1}$		6	pF
	$\overline{RAS}$ , $\overline{OE}$ , $\overline{CAS}$ , $\overline{WE}$	$C_{IN2}$		7	pF
Input/output capacitance	$I/O_1 - I/O_4$	$C_{OUT1}$		7	pF

**DC ELECTRICAL CHARACTERISTICS ( $T_A = 0$  to  $+70^\circ\text{C}$ ,  $V_{CC} = 3.3$  V  $\pm 0.3$  V)**

PARAMETER	CONDITIONS	SYMBOL	MIN.	MAX.	UNIT	NOTE
Average supply current in normal operation		$I_{CC1}$		35	mA	1, 2, 3
Supply current in standby mode	$\overline{RAS} = \overline{CAS} \geq V_{CC} - 0.2$ V	$I_{CC2}$		0.15	mA	1
Average supply current in fast page mode		$I_{CC3}$		30	mA	1, 2
Average supply current in $\overline{CAS}$ before $\overline{RAS}$ refresh cycle		$I_{CC4}$		35	mA	1, 2, 3
Average supply current in $\overline{RAS}$ only refresh cycle		$I_{CC5}$		35	mA	1, 2, 3
Input leakage current	$0$ V $\leq V_{IN} \leq 4.8$ V 0 V except on test pins	$I_{LI}$	-10	10	$\mu$ A	
Output leakage current	$0$ V $\leq V_{OUT} \leq 4.8$ V Output in high-impedance state	$I_{LO}$	-10	10	$\mu$ A	
Output 'High' Voltage	$I_{OUT} = -200$ $\mu$ A	$V_{OH}$	2.15		V	
Output 'Low' Voltage	$I_{OUT} = 1$ mA	$V_{OL}$		0.4	V	

**NOTES:**

1. Specified values are with outputs open.
2.  $I_{CC1}$ ,  $I_{CC3}$ ,  $I_{CC4}$ , and  $I_{CC5}$  depend on cycle time.
3. Cycle time is 190 ns. Address transition is once at  $\overline{RAS} = V_{IH}$  and once at  $\overline{RAS} = V_{IL}$ .

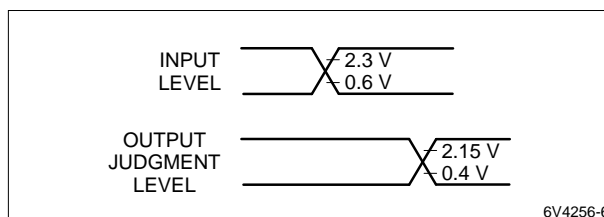
AC ELECTRICAL CHARACTERISTICS <sup>1, 2, 3, 4</sup> (T<sub>A</sub> = 0 to +70°C, V<sub>CC</sub> = 3.3 V ±0.3 V)

READ CYCLE

PARAMETER	SYMBOL	MIN.	MAX.	UNIT	NOTE
Random read or write cycle time	t <sub>RC</sub>	190		ns	
Access time from RAS	t <sub>RAC</sub>		100	ns	5
Access time from column address	t <sub>AA</sub>		50	ns	5
Access time from CAS	t <sub>CAC</sub>		40	ns	5
Access time from OE	t <sub>OEA</sub>		35	ns	5
Row address setup time	t <sub>ASR</sub>	0		ns	
Row address hold time	t <sub>RAH</sub>	15		ns	
Column address setup time	t <sub>ASC</sub>	0		ns	
Column address hold time (RAS)	t <sub>CAH</sub>	20		ns	
Column address delay time (RAS)	t <sub>RAD</sub>	20	50	ns	6
Column address lead time (RAS)	t <sub>RAL</sub>	50		ns	
RAS pulse width	t <sub>RAS</sub>	100	10,000	ns	
RAS precharge time	t <sub>RP</sub>	80		ns	
CAS precharge time (RAS ↓)	t <sub>CRP</sub>	0		ns	
CAS delay time (RAS)	t <sub>RCD</sub>	25	60	ns	7
CAS lead time (RAS)	t <sub>RSL</sub>	30		ns	
CAS pulse width	t <sub>CAS</sub>	40	10,000	ns	
CAS hold time	t <sub>CSH</sub>	100		ns	
OE lead time (RAS)	t <sub>ROL</sub>	0		ns	
Output data disable time (CAS)	t <sub>OFF</sub>		30	ns	
Output data disable time (OE)	t <sub>OEZ</sub>		30	ns	
Output data hold time (CAS)	t <sub>SOH</sub>	0		ns	
Output data hold time (OE)	t <sub>OOH</sub>	0		ns	
Read command setup time (CAS)	t <sub>RCS</sub>	0		ns	
Read command hold time (CAS)	t <sub>RCH</sub>	10		ns	8
Read command hold time (RAS ↑)	t <sub>RRHP</sub>	10		ns	8
Read command hold time (RAS ↓)	t <sub>RRHN</sub>	115		ns	8
Transition time (rise and fall)	t <sub>T</sub>	3	35	ns	
Refresh time interval	t <sub>REF</sub>		8	ms	

NOTES:

- For proper memory function, at least 200 μs of pause time should be kept after power on, followed by several dummy cycles. When RAS = V<sub>IH</sub> is continued for more than 8 ms, the same dummy cycles should be given. Usually eight ordinary refresh cycles should be given.
- The required V<sub>CC</sub> current (I<sub>CC</sub>) during power on depends on the input levels of RAS. If RAS = V<sub>IL</sub> during power on, the device goes into an active cycle, and I<sub>CC</sub> exhibits large current transients. It is recommended that RAS tracks with V<sub>CC</sub> or be held at a valid V<sub>IH</sub> during power on.
- AC characteristics assume t<sub>T</sub> = 5 ns.
- AC characteristics assume the following condition (see figure at right).
- Load condition for 1TTL + 30 pF.
- t<sub>RAD</sub> (MAX) is the maximum point for t<sub>RAD</sub> where t<sub>RAC</sub> (MAX) is ensured, and does not represent a limit of operation. If t<sub>RAD</sub> ≥ t<sub>RAD</sub> (MAX), the access time comes under the control of t<sub>AA</sub>.
- t<sub>RCD</sub> (MAX) is the maximum point for t<sub>RCD</sub>, where t<sub>RAC</sub> (MAX) is ensured and does not represent a limit of operation. If t<sub>RCD</sub> ≥ t<sub>RCD</sub> (MAX), the access time comes under the control of t<sub>CAC</sub>.
- The operation is ensured when either t<sub>RRHN</sub>, t<sub>RRHP</sub>, or t<sub>RCH</sub> is satisfied.



**FAST PAGE MODE CYCLE**

PARAMETER	SYMBOL	MIN.	MAX.	UNIT	NOTE
Fast page mode cycle time	$t_{PC}$	60		ns	
CAS precharge time	$t_{CP}$	10		ns	
CAS precharge access time	$t_{CACP}$		55	ns	
Read-write cycle time (page mode)	$t_{PRWC}$	125		ns	1

**NOTE:**

1.  $t_{RWC}$ ,  $t_{RWD}$ ,  $t_{AWD}$ ,  $t_{CWD}$ , and  $t_{PRWC}$  are not restrictive operating parameters and does not represent a limit of operation.

**WRITE CYCLE**

PARAMETER	SYMBOL	MIN.	MAX.	UNIT	NOTE
<b>EARLY WRITE</b>					
Write command setup time ( $\overline{CAS}$ )	$t_{WCS}$	0		ns	1
Write command hold time ( $\overline{CAS}$ )	$t_{WCH}$	15		ns	
Data input setup time	$t_{DS}$	0		ns	
Data input hold time	$t_{DH}$	20		ns	
<b>OE CONTROLLED</b>					
CAS setup time	$t_{CWS}$	0		ns	1
Write command lead time ( $\overline{RAS}$ )	$t_{RWL}$	30		ns	
Write command lead time ( $\overline{CAS}$ )	$t_{CWL}$	25		ns	
Write pulse width ( $\overline{WE}$ )	$t_{WP}$	15		ns	
$\overline{OE}$ hold time ( $\overline{WE}$ )	$t_{OEH}$	20		ns	

**NOTE:**

1.  $t_{WCS}$  and  $t_{CWS}$  are not restrictive operating parameters. If  $t_{WCS} \geq t_{WCS}(\text{MIN})$ , the cycle is an early write cycle and data out buffers remain inactive until  $\overline{CAS}$  rises again.

**READ-WRITE CYCLE/READ-MODIFY-WRITE CYCLE**

PARAMETER	SYMBOL	MIN.	MAX.	UNIT	NOTE
Read-write cycle time	$t_{RWC}$	260		ns	1
$\overline{WE}$ delay time ( $\overline{RAS}$ )	$t_{RWD}$	135		ns	1
Column address delay time ( $\overline{WE}$ )	$t_{AWD}$	85		ns	1
$\overline{WE}$ delay time ( $\overline{CAS}$ )	$t_{CWD}$	65		ns	1
$\overline{OE}$ delay time	$t_{OED}$	25		ns	

**NOTE:**

1.  $t_{RWC}$ ,  $t_{RWD}$ ,  $t_{AWD}$ ,  $t_{CWD}$ , and  $t_{PRWC}$  are not restrictive operating parameters and does not represent a limit of operation.

**CAS BEFORE RAS REFRESH CYCLE/HIDDEN REFRESH CYCLE**

PARAMETER	SYMBOL	MIN.	MAX.	UNIT
$\overline{CAS}$ setup time ( $\overline{RAS}$ )	$t_{CSR}$	0		ns
CAS hold time ( $\overline{RAS}$ )	$t_{CHR}$	20		ns
$\overline{RAS} \cdot \overline{CAS}$ precharge time ( $\overline{RAS} \uparrow$ )	$t_{RPCP}$	10		ns
$\overline{RAS} \cdot \overline{CAS}$ precharge time ( $\overline{RAS} \downarrow$ )	$t_{RPCN}$	115		ns
$\overline{WE}$ precharge time ( $\overline{RAS}$ )	$t_{WRP}$	0		ns

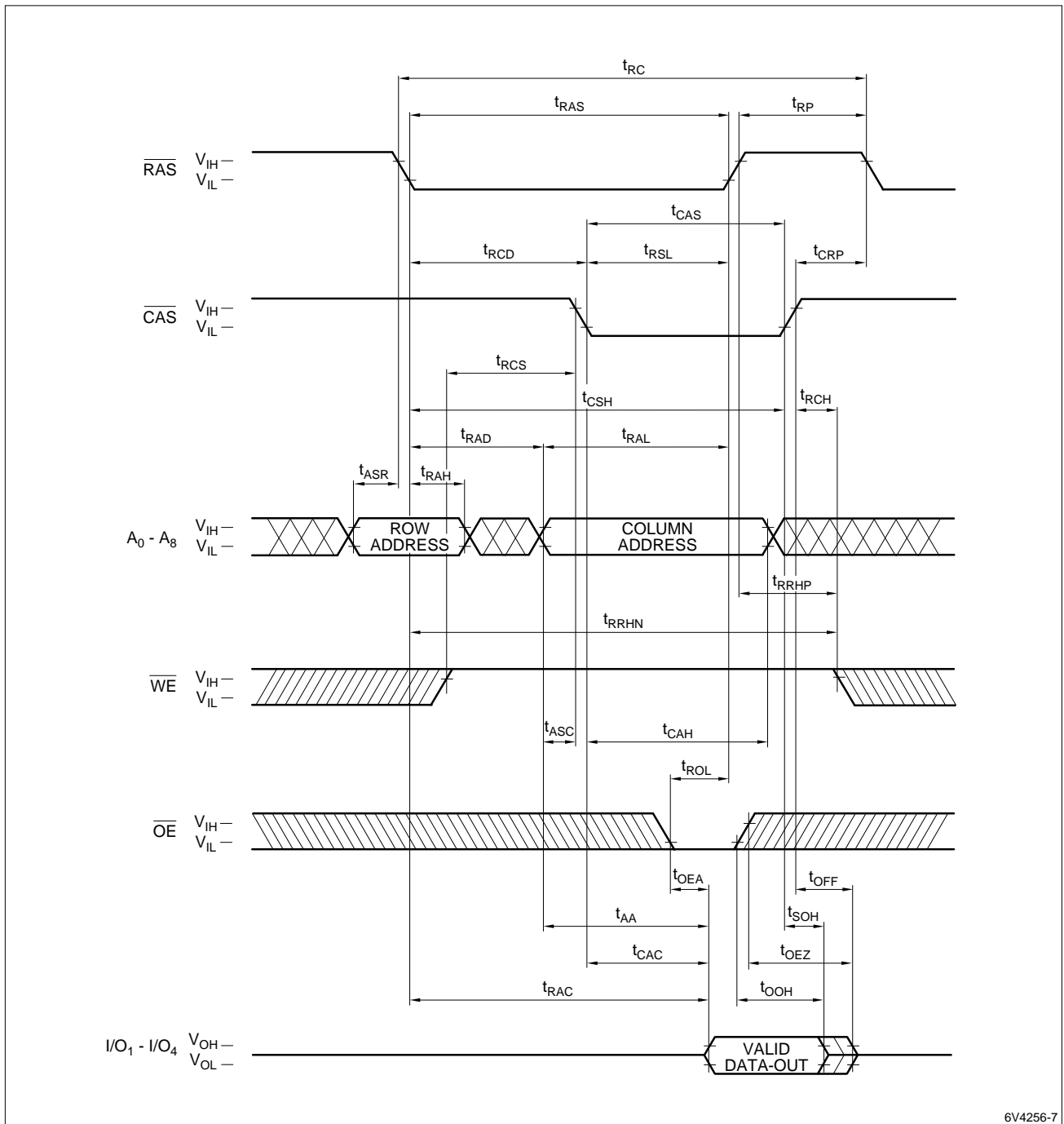


Figure 6. Read Cycle



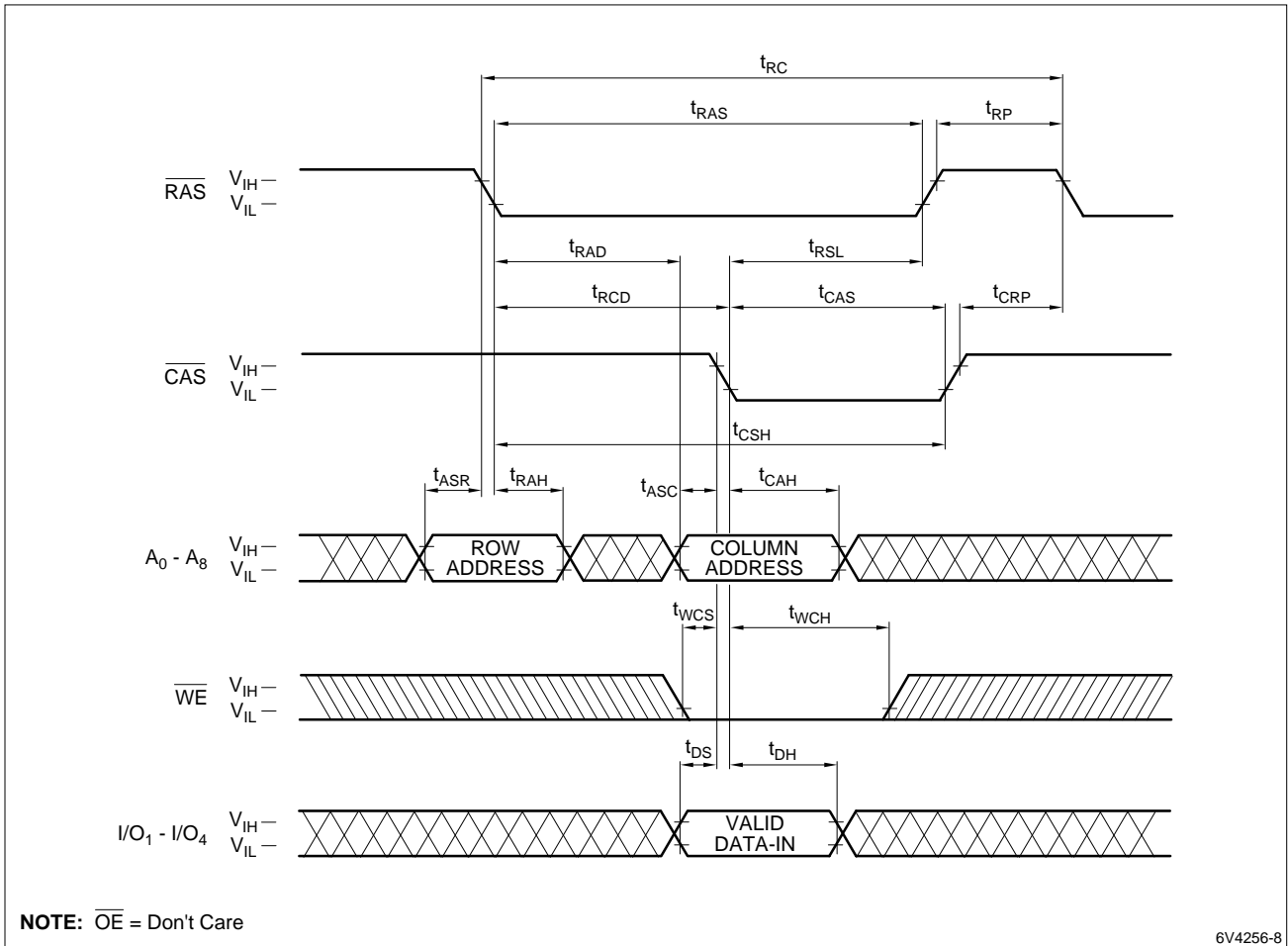
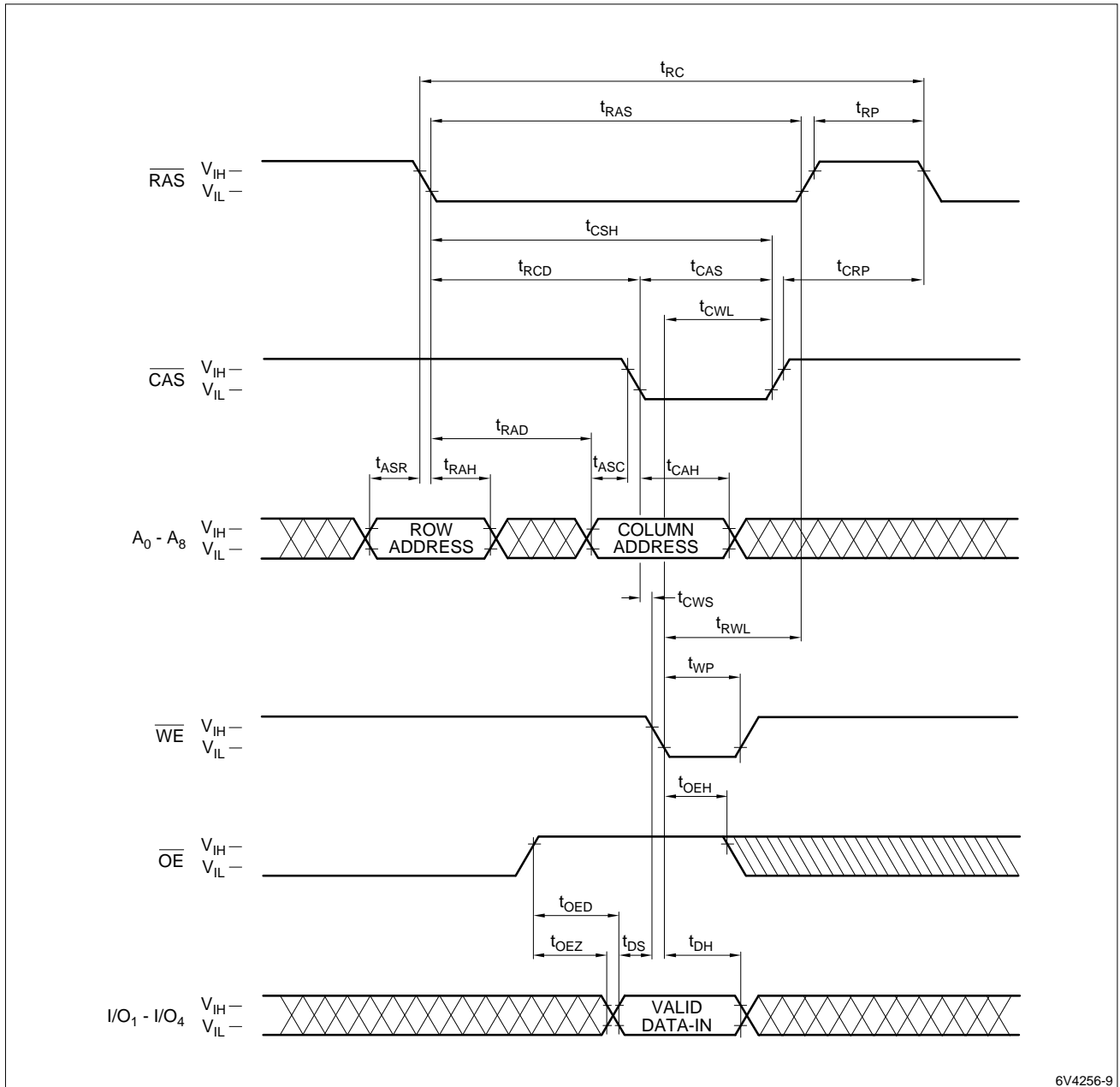
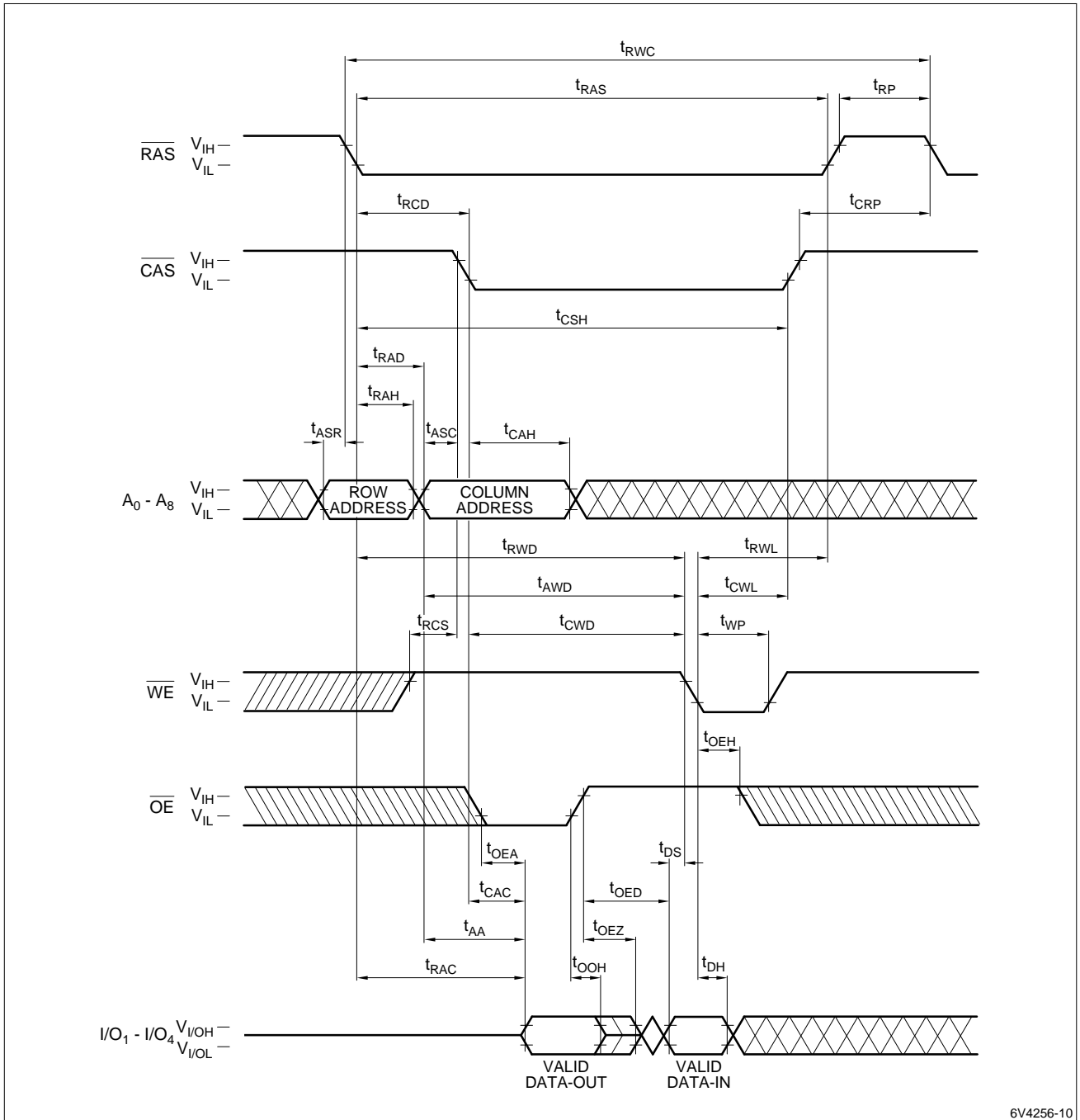


Figure 7. Write Cycle (Early Write)



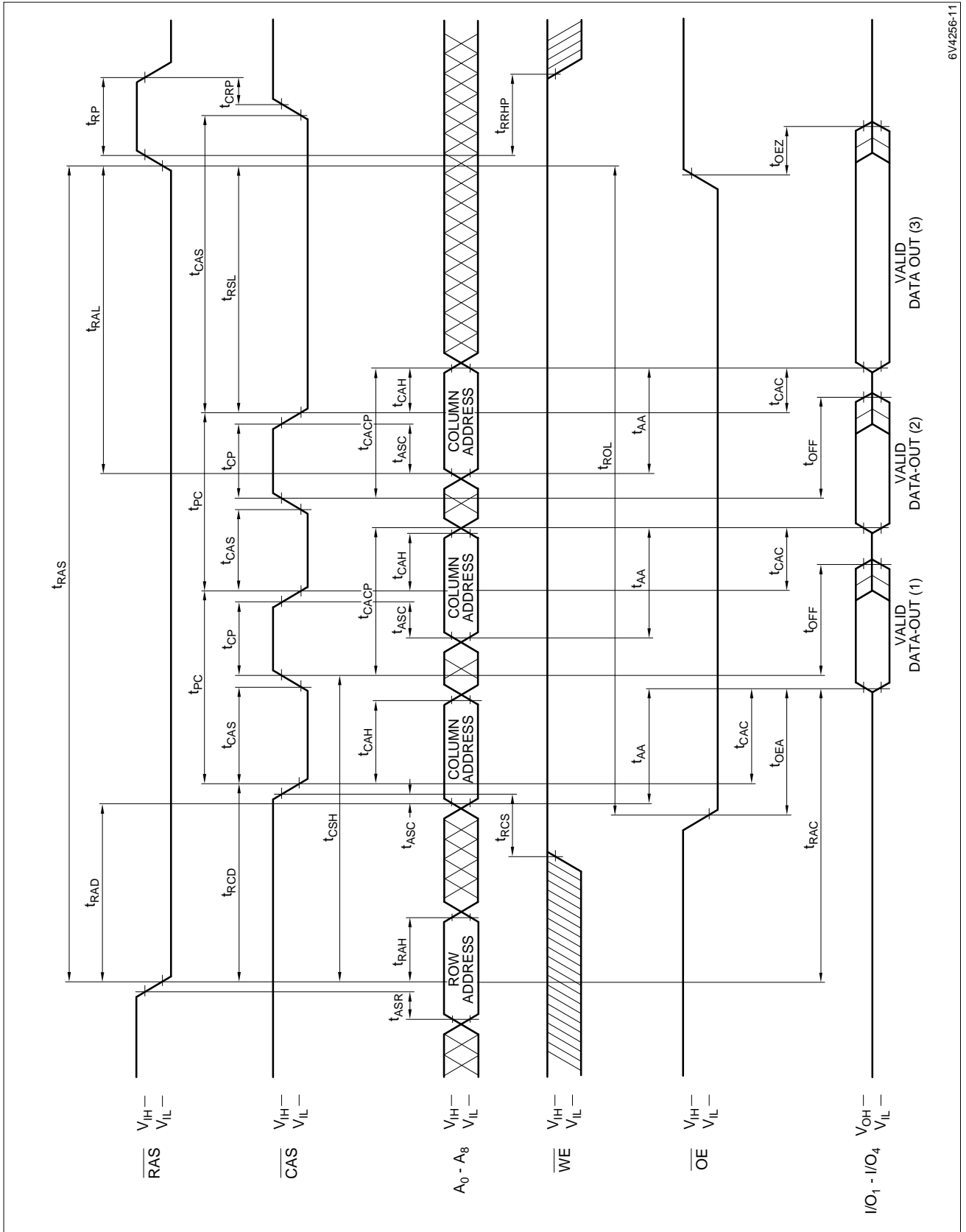
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Figure 8. Write Cycle ( $\overline{OE}$  Controlled Write)



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Figure 9. Read/Write Cycle



6V4256-11

Figure 10. Fast Page Mode Read Cycle

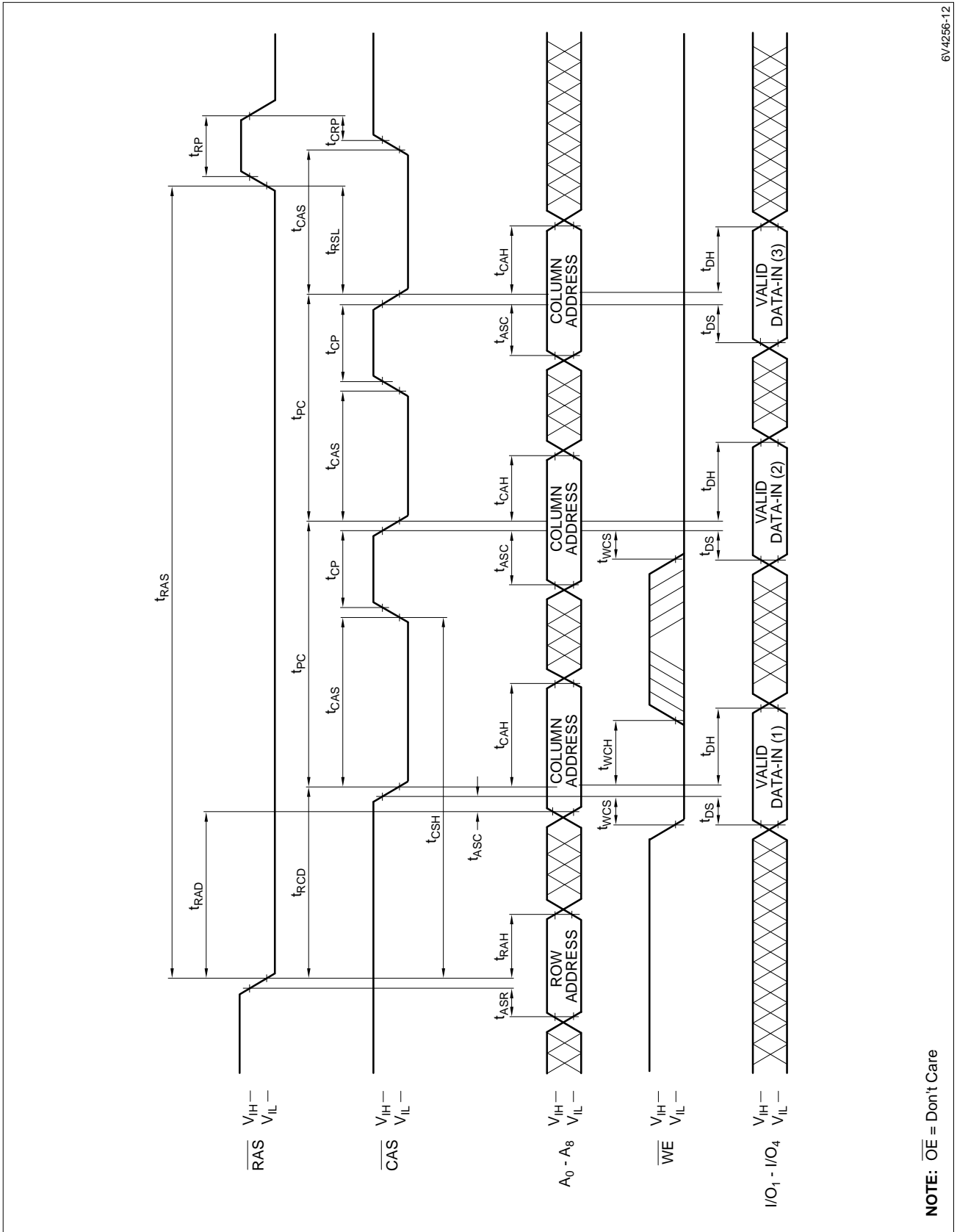
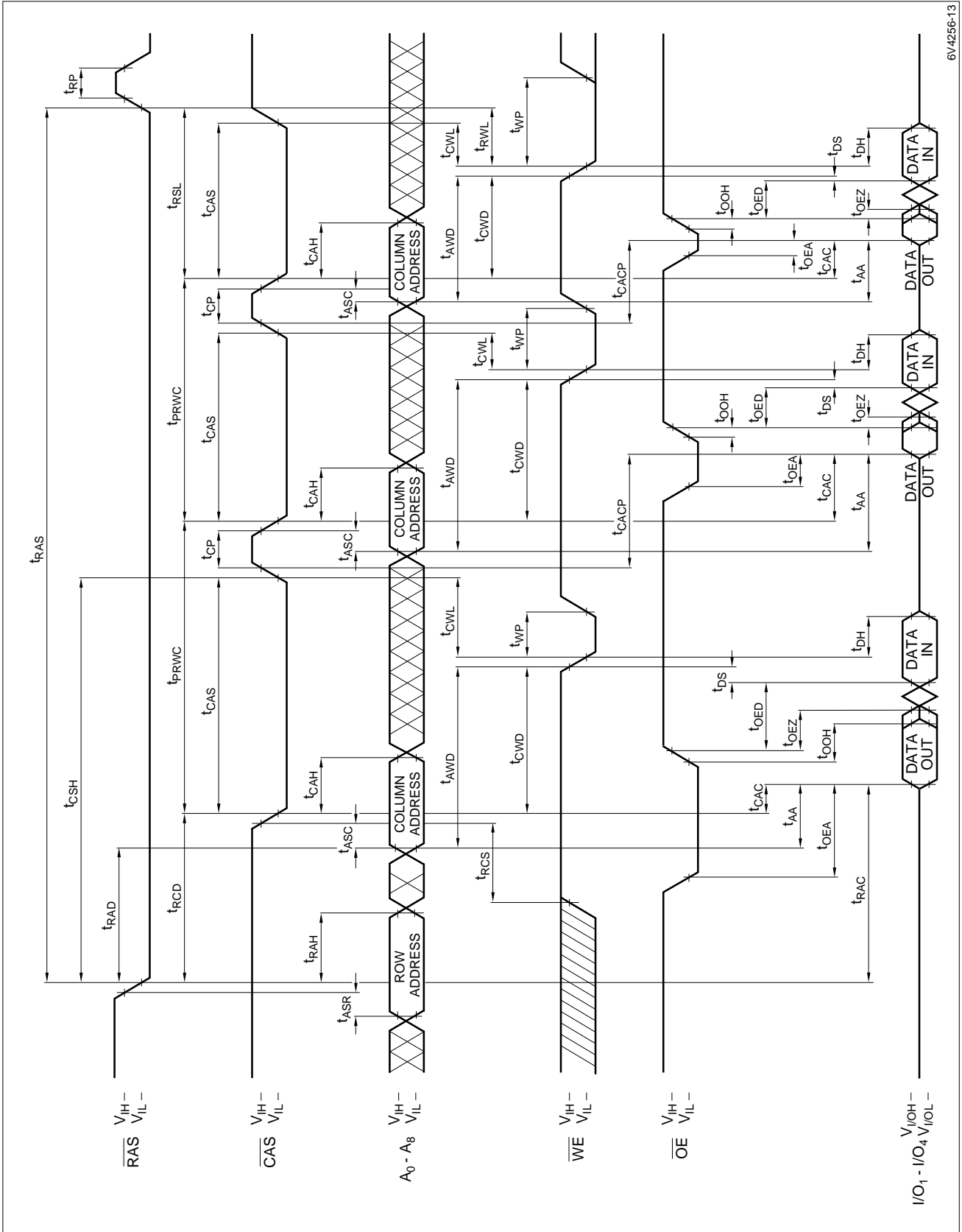


Figure 11. Fast Page Mode Write Cycle



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Figure 12. Fast Page Mode Read/Write Cycle

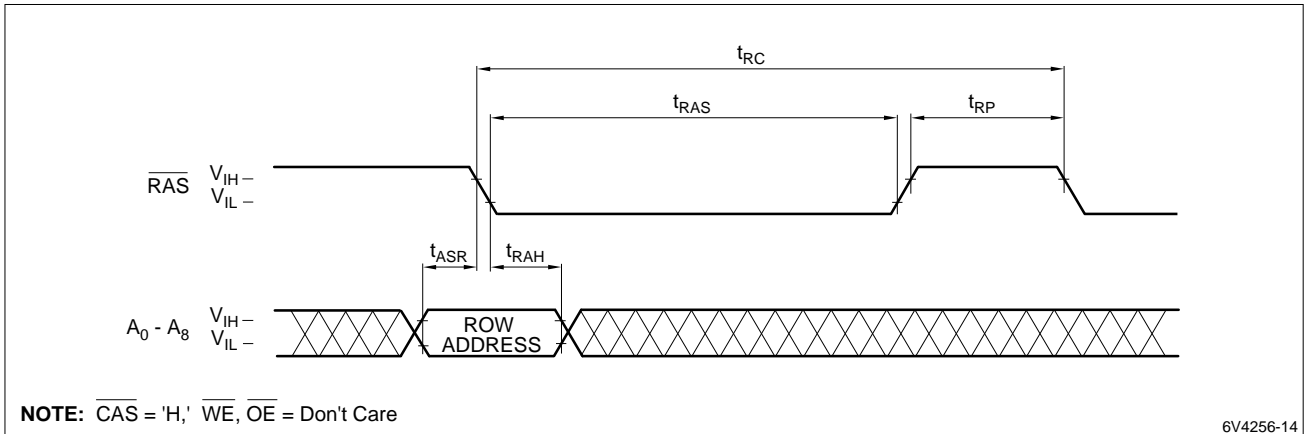


Figure 13.  $\overline{\text{RAS}}$  Only Refresh Cycle

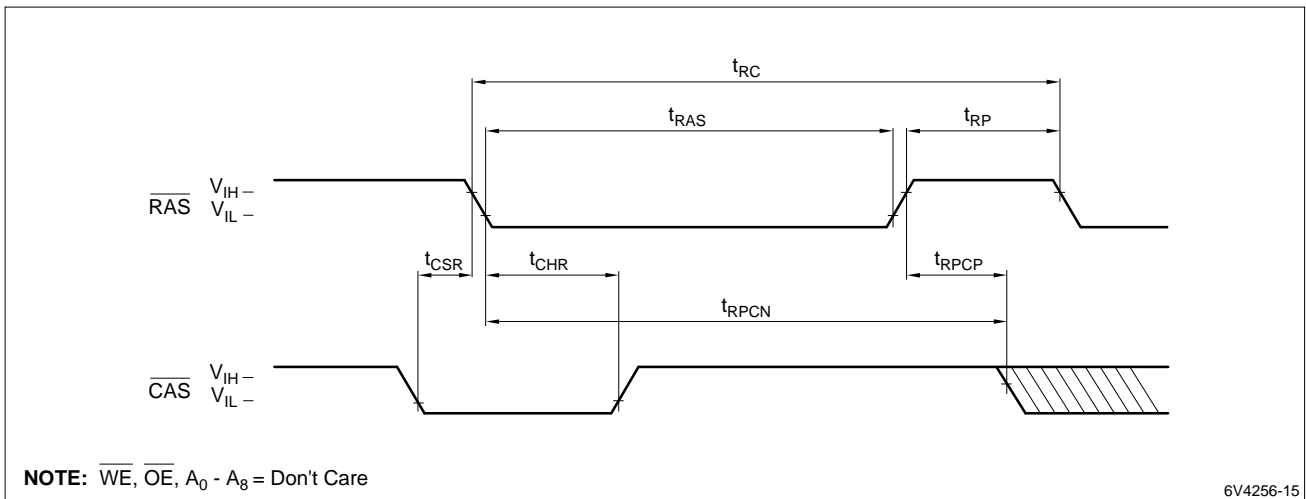
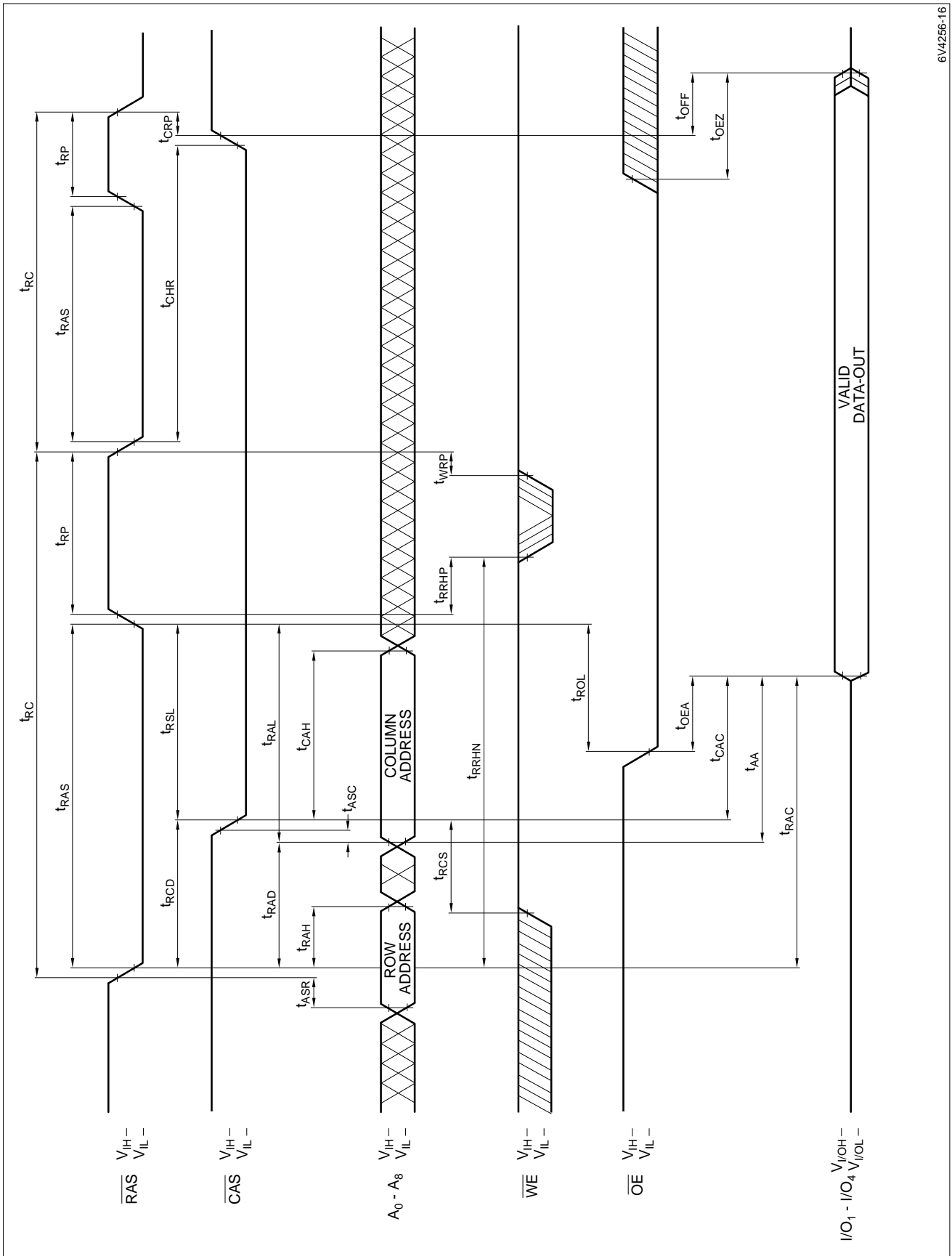


Figure 14.  $\overline{\text{CAS}}$  Before  $\overline{\text{RAS}}$  Refresh Cycle

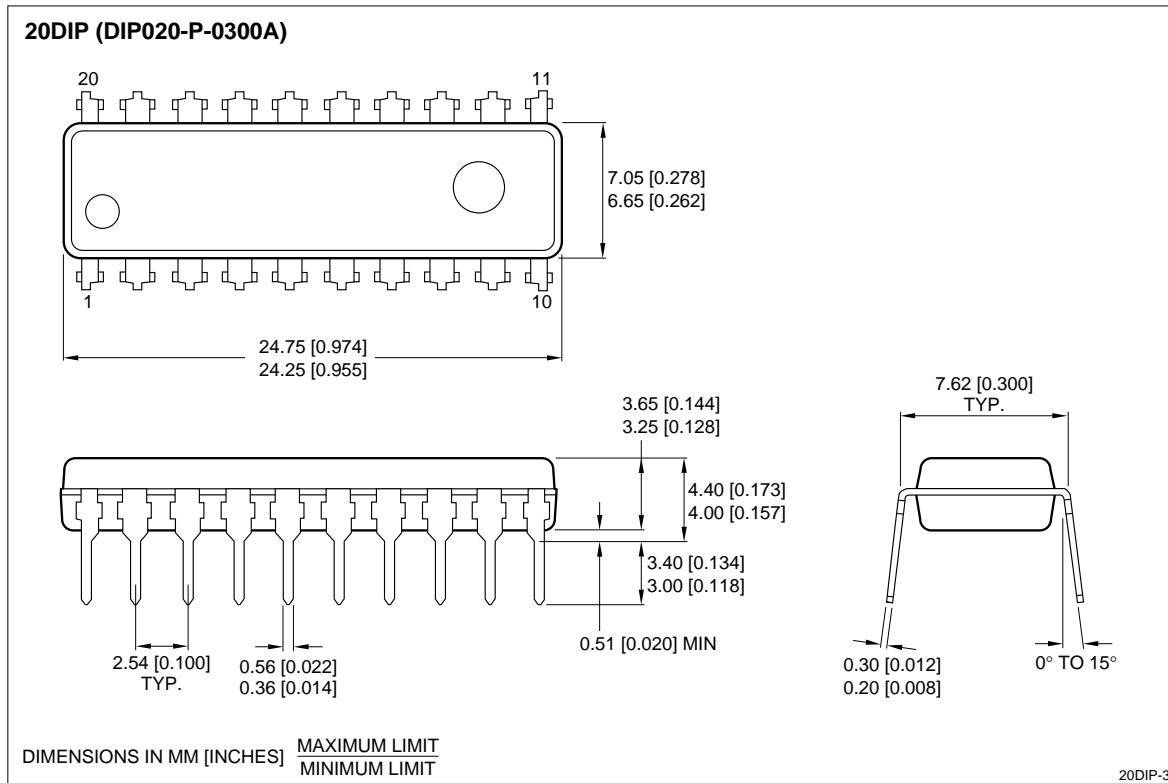


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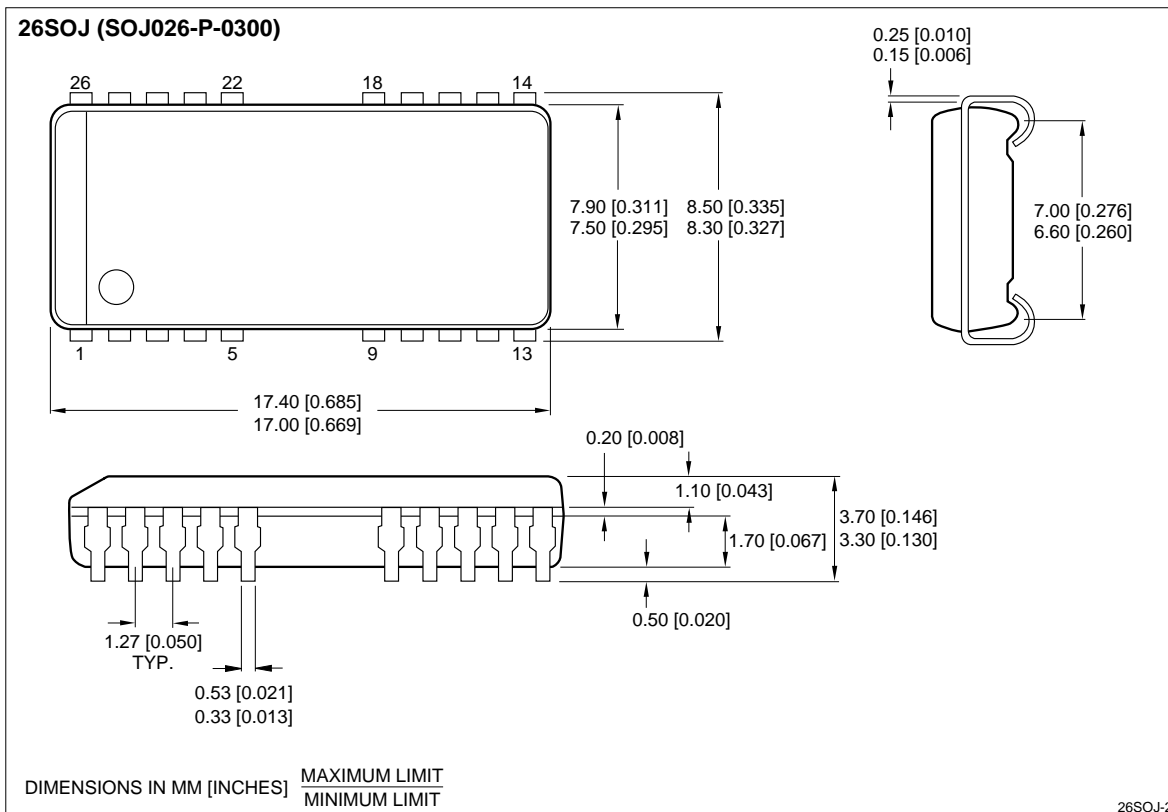
Figure 15. Hidden Refresh Cycle



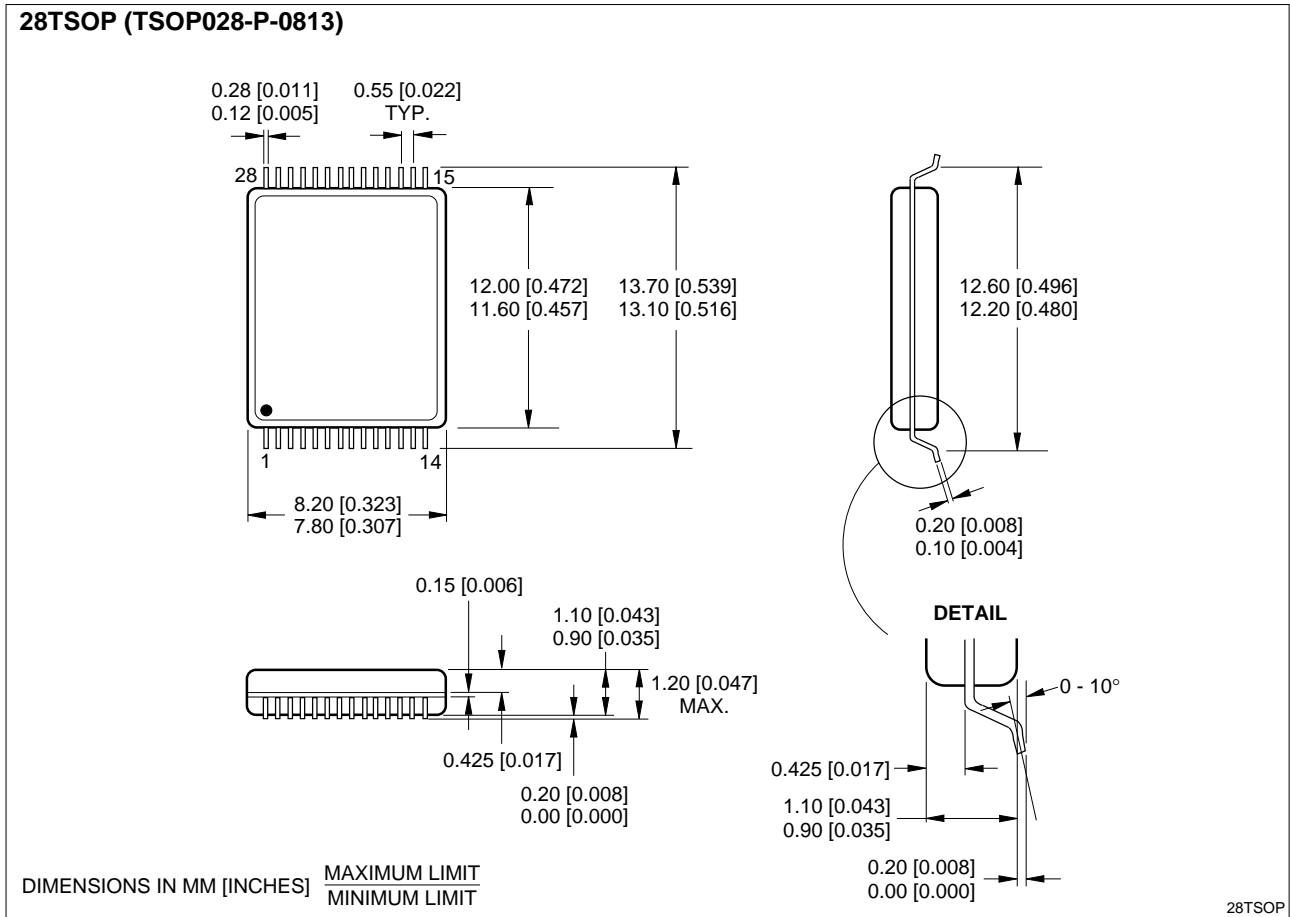
PACKAGE DIAGRAMS



20-pin, 300-mil DIP



26-pin, 300-mil SOJ



**28-pin, 8 × 13 mm<sup>2</sup> TSOP (Type I)**

**ORDERING INFORMATION**

